+44 20 8123 2220
info@marketpublishers.com

Global Semiconductor Lead Frame Market Size Study & Forecast, by Packaging Type (DIP, SOP, SOT, QFP, DFN, QFN , FCF, Others), by Application (Integrated Circuit, Discrete Device, Others), by Industry Vertical (Consumer Electronics, Industrial and Commercial Electronics, Automotive, Others), and Regional Analysis, 2023-2030

https://marketpublishers.com/r/G904FF8879F1EN.html
Date: October 2023
Pages: 200
Price: US$ 4,950.00 (Single User License)
ID: G904FF8879F1EN

Abstracts

Global Semiconductor Lead Frame Market is valued at approximately USD 3.40 billion in 2022 and is anticipated to grow with a healthy growth rate of more than 6.9% over the forecast period 2023-2030. A semiconductor lead frame is a crucial component as it serves as a structural support and electrical connection platform for the semiconductor die within the package. These lead frames are utilized in semiconductor packages such as flat packages, small outline packages, and integrated circuits (ICs). The main driver of the market is the rapid adoption of semiconductor lead frames on PCB boards to support and fix IC chips and lead frames for pins. It enhances chip performance and allows for extended operating durations. Additionally, these lead frame packages are gaining high traction in almost all semiconductor devices that transmit electricity to specific circuits on the PCB board. Lead frame is the main component of consumer electronic gadgets due to its widespread usage in semiconductor packing and Integrated Circuits (ICs). The surging demand for semiconductors across various industries, as well as the rising trend towards miniaturization and higher integration of electronic devices and integrated circuits, are further attributing to the market growth across the globe.

In addition, the spurring demand for consumer electronics such as smartphones, wearable devices, tablets, and smart home appliances is primarily associated with the

+44 20 8123 2220
info@marketpublishers.com

adoption of the semiconductor lead frame, which is accelerating the market growth during the estimated period. These devices require efficient semiconductor packaging solutions, including lead frames, to ensure reliable electrical connections and thermal management. According to Statista, in 2022, the consumer electronics and appliances segment was estimated to account for USD 455.15 billion, which is a rise of USD 204.23 billion in 2015. Thus, these aforementioned factors are propelling the growth of the semiconductor lead frame market during the estimated period. Moreover, the ongoing advancements in semiconductor packaging technologies, as well as the increased use of electronic components and systems across the automotive industry present various lucrative opportunities over the forecast years. However, the fluctuations in the prices of raw materials and the availability of other packaging technologies are challenging the market growth throughout the forecast period of 2023-2030.

The key regions considered for the Global Semiconductor Lead Frame Market study include Asia Pacific, North America, Europe, Latin America, and Middle East & Africa. North America dominated the market in 2022 owing to the surging adoption of connected devices, rising favorable policies and initiatives by the government, coupled with the continuous development of lead frame technologies by key market players. Whereas, Asia Pacific is expected to grow at the highest CAGR over the forecast years. The rapid adoption of consumer electronics and IoT devices, increase in investments by leading players, government initiatives for developing the semiconductor industry, and growing research and development activities are significantly propelling the market demand across the region.

Major market players included in this report are:

Mitsui High-tec, Inc. (Japan)

Shinko Electric Industries Co., Ltd. (Japan)

Chang Wah Technology Co., Ltd (China)

Haesungds (Korea)

ASMPT Corporate (Singapore)

Ningbo Hualong Electronics Co., Ltd (China)

+44 20 8123 2220
info@marketpublishers.com

Wuxi Huajing Leadframe Co., Ltd (China)

QPL Limited (Hong Kong)

SDI Group, Inc. (Taiwan)

Dynacraft Industries Sdn Bhd (Malaysia)

Recent Developments in the Market:

In May 2021, Chang Wah Technology (CWTC), a Taiwan-based lead frame manufacturer, aims to increase manufacturing capabilities for IC packaging to meet the high demand for automotive control modules and power management units.

In October 2021, Dai Nippon Printing Co., Ltd. - the Japanese printing company unveiled high-definition HD silver-coated lead frames. These lead frames offer better adhesiveness and roughness in order to comply with strict industrial standards.

Global Semiconductor Lead Frame Market Report Scope:

Historical Data – 2020 - 2021

Base Year for Estimation – 2022

Forecast period - 2023-2030

Report Coverage - Revenue forecast, Company Ranking, Competitive Landscape, Growth factors, and Trends

Segments Covered - Packaging Type, Application, Industry Vertical, Region

Regional Scope - North America; Europe; Asia Pacific; Latin America; Middle East & Africa

Customization Scope - Free report customization (equivalent up to 8 analyst's working hours) with purchase. Addition or alteration to country, regional &

+44 20 8123 2220
info@marketpublishers.com

segment scope*

The objective of the study is to define market sizes of different segments & countries in recent years and to forecast the values to the coming years. The report is designed to incorporate both qualitative and quantitative aspects of the industry within countries involved in the study.

The report also caters detailed information about the crucial aspects such as driving factors & challenges which will define the future growth of the market. Additionally, it also incorporates potential opportunities in micro markets for stakeholders to invest along with the detailed analysis of competitive landscape and product offerings of key players. The detailed segments and sub-segment of the market are explained below:

By Packaging Type:

DIP (Dual Inline Pin Package)

SOP (Small Out-Line Package)

SOT (Small Outline Transistor)

QFP (Quad Flat Pack)

DFN (Dual Flat No-Leads)

QFN (Quad Flat No-Leads)

FCF (Flip Chip)

Others

By Application:

Integrated Circuit

Discrete Device

Others

+44 20 8123 2220
info@marketpublishers.com

By Industry Vertical:

Consumer Electronics

Industrial and Commercial Electronics

Automotive

Others

By Region:

North America

U.S.

Canada

Europe

UK

Germany

France

Spain

Italy

ROE

Asia Pacific

China

India

+44 20 8123 2220
info@marketpublishers.com

Japan

Australia

South Korea

RoAPAC

Latin America

Brazil

Mexico

Middle East & Africa

Saudi Arabia

South Africa

Rest of Middle East & Africa

+44 20 8123 2220
info@marketpublishers.com

Contents

+44 20 8123 2220
info@marketpublishers.com

+44 20 8123 2220
info@marketpublishers.com

+44 20 8123 2220
info@marketpublishers.com

CHAPTER 9. COMPETITIVE INTELLIGENCE

+44 20 8123 2220
info@marketpublishers.com

CHAPTER 10. RESEARCH PROCESS

+44 20 8123 2220
info@marketpublishers.com

I would like to order

Product name: Global Semiconductor Lead Frame Market Size Study & Forecast, by Packaging Type (DIP, SOP, SOT, QFP, DFN, QFN , FCF, Others), by Application (Integrated Circuit, Discrete Device, Others), by Industry Vertical (Consumer Electronics, Industrial and Commercial Electronics, Automotive, Others), and Regional Analysis, 2023-2030

Product link: https://marketpublishers.com/r/G904FF8879F1EN.html

Price: US$ 4,950.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/G904FF8879F1EN.html

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

**All fields are required

Custumer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at https://marketpublishers.com/docs/terms.html

+44 20 8123 2220
info@marketpublishers.com

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970